

Declaration and Power of Attorney for a Patent Application

Declaration

As below named inventor, I hereby declare that my residence post office address, and citizenship are as stated below my name. Further, I hereby declare that I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

FLIP-CHIP PACKAGING

the specification of which:

..... is attached hereto, or
☒ was filed on 08/09/02 as application serial no. 10/215,570 : and
 was amended on

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above; and

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, Section 1.56(a).

Foreign Priority Claim

I hereby claim foreign priority benefits under Title 35, United States Code Section 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Number	Country	Date Filed	Priority Claimed
.....	yes no
.....	yes no

U.S. Priority Claim

I hereby claim the benefit under Title 35, United States Code, Section 120 and 199(e) of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, Section 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, Section 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

Serial Number	Filing Date	Status (patented/pending/abandoned)
.....
.....

Power of Attorney

As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent Trademark Office connected therewith.

James P. Hao	Registration No.: 36,398
Anthony C. Murabito	Registration No.: 35,295
John P. Wagner	Registration No.: 35,398
Glenn D. Barnes	Registration No.: 42,293
Thomas M. Catale	Registration No.: 46,434
Jose S. Garcia	Registration No.: 43,628
Eric J. Gash	Registration No.: 46,274
Lin C. Hsu	Registration No.: 46,315
Ronald M. Pomerence	Registration No.: 43,009
John F. Ryan	Registration No.: 47,050
Matthew J. Blecher	Registration No.: 46,558
Lawrence R. Goerke	Registration No.: 45,927
Reginald A. Ratliff	Registration No.: 48,098
William A. Zarbis	Registration No.: 46,120
Mehlin Dean Matthews	Registration No.: 46,127
Joel D. Youngs	Registration No.: P-52,389

Send Correspondence to:

WAGNER, MURABITO & HAO LLP
Two North Market Street
Third Floor
San Jose, California 95113
(408) 938-9060

Signatures

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full Name of Sole/First Inventor: William Planey

Inventor's Signature William Planey Date 2/13/02
Residence Plano, Texas Citizenship USA
(City State)
P.O. Address 3600 Tree Shadow Trail, Plano, Texas 75074

Assignment to Lovoltech Inc.

In consideration of good and valuable consideration, receipt of which is hereby acknowledged, I/we

William Planey
do hereby sell, assign, and transfer unto Lovoltech Inc. (hereinafter called Lovoltech), a California Corporation having its principal place of business at 3970 Freedom Circle, Santa Clara, CA 95054, and its successors and assigns, the entire right, title, and interest for the United States and all foreign countries, in and to any and all improvements, including the right of priority in, to, and under, the application for the United States patent entitled:

FLIP-CHIP PACKAGING

..... filed herewith and the inventions set forth and described therein, and any and all Letters Patent of the United States and of countries foreign thereto which may be granted thereon or therefor; or

☒ Serial No.: 10/215,570 filed on 08/09/02 and the inventions set forth and described therein, and any and all Letters Patent of the United States and of countries foreign thereto which may be granted thereon or therefor;

And for the above consideration, I/we agree promptly upon request of Lovoltech, its successors or assigns, to execute and deliver without further compensation any power of attorney, assignment, application, whether original, continuation, divisional or reissue, or other papers which may be necessary or desirable fully to secure to, its successors and assigns, the inventions described in said application and all patent rights therein, in the United States and in any country foreign thereto, and to cooperate and assist in the prosecution of interference proceedings involving said inventions and in the adjudication or reexamination of said Letters Patent provided the expenses which may be incurred by me/us in lending such cooperation and assistance are paid by Lovoltech.

I/we further covenant with Lovoltech, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned;

In witness whereof, I/we hereunto set my/our hand(s) and seal:

Inventor's Signature: William B. Planey Date: Dec 2, 2003

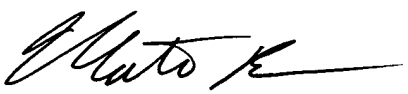
Inventor(s): William Planey

Title: FLIP-CHIP PACKAGING

**REQUEST AND CERTIFICATION
UNDER 35 U.S.C. 122(b)(2)(B)(i)**

I hereby certify that the invention disclosed in the attached application **has not and will not be** the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing. I hereby request that the attached application not be published under 35 U.S.C. 122(b).

Date: Dec 5, 2003

By: 
Matthew J. Blecher
Reg. No. 46,558

This request must be signed in compliance with 37 CFR 1.33(b) and submitted with the application **upon filing**.

Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant must notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. **Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).**

Notification to Parent of Continuing Application Filing

Applicant: **w. planey**

Filed: **08/09/02**

Docket No.: **LOVO-51**

Serial No.: **10/215,570**

Title: **FLIP-CHIP PACKAGING**

Sir:

Please acknowledge receipt of the following:

- ☒ Certificate of Mailing
- ☒ Conditional Petition for an Extension of Time
- ☒ Notification of Filing of a Continuing Application

rev. 12/97 dbp

submitted
12/5/03